

Applications

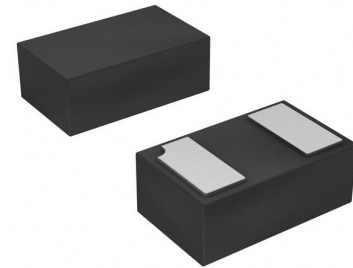
- Lan equipment
- Video
- DVI
- High Speed Data Line
- Ethernet
- USB 2.0 Power and Data line Protection

Feature

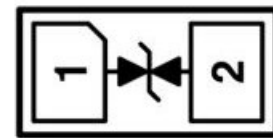
- With TVS Diode
- ESD Protection:Level 4
- Low clamping voltage
- 75Watts peak pulse power per line(tp=8/20uS)
- Ultra low capacitance:20pf max.(any I/O to GND.)
- Protection one line I/O port

IEC Compatibility

- EN61000-4
- 61000-4-2(ESD):LEVEL 4,Air:8kv,contact:15kv
- 61000-4-4(EFT):40A-5/50ns
- 61000-4-5(Surge):3A-8/20us



DFN1006-2L


Mechanical Characteristics

- Molded JEDEC DFN1006 package
- Packing:Tape and Reel
- Flammability rating UL 94V-0
- Halgen Free

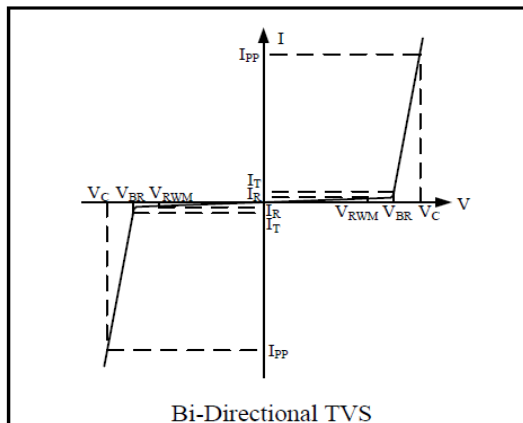
Device Characteristics

Maximum Ratings@25 unless otherwise specified			
Parameter	Symbol	Value	Units
Peak pulse power (tp=8/20us)	PPP	75	Watts
Operating Temperature	TJ	-55~150	°C
Storage Temperature	TSTG	-65~150	°C

Electrical Characteristics

Parameter	Symbol	Condition	min	max	Units
Reverse Stand-off Voltage	V_{RWM}	Pin 2-1/Pin 1-2		5	V
Reverse Breakdown Voltage	V_{BR}	$I_Z=1mA$ Pin 1-2/pin 2-1	6.0	9.0	V
Reverse Leakage Current	$I_R(max)$	@ V_{RWM}		2	μA
Forward Voltage	$V_F(max)$	$I_F=15mA$		1.15	V
Clamping Voltage	V_C	$I_{PP}=1A$ $t_p=8/20\mu s$		15	V
Peak Pulse Current	I_{PP}	$t_p=8/20\mu s$		3	A
Junction Capacitance	$C_{I/O}$	Pin capacitance to GND. $V_{dc}=0V, f=1MHz$		15	pf

Symbol	Parameter
V_{RWM}	Nominal Reverse Working Voltage
I_R	Reverse Leakage Current @ V_{RWM}
V_{BR}	Reverse Breakdown Voltage @ I_T
I_T	Test Current for Reverse Breakdown
V_C	Clamping Voltage @ I_{PP}
I_{PP}	Maximum Peak Pulse Current
C_{ESD}	Parasitic Capacitance
V_R	Reverse Voltage
f	Small Signal Frequency



Bi-Directional TVS

Rating and characteristic curve

FIG 1
Power Derating Curve

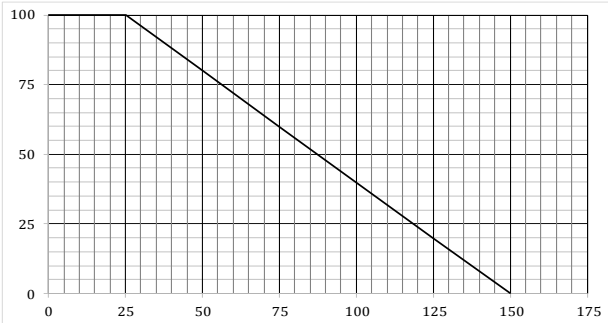
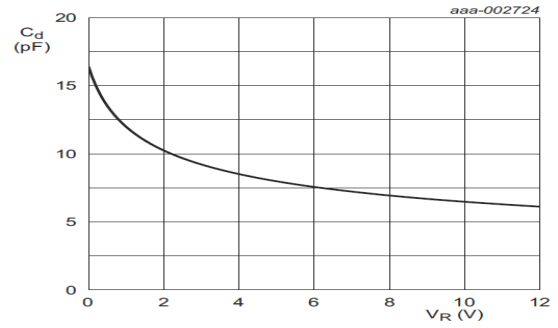


FIG 2.
Capacitance



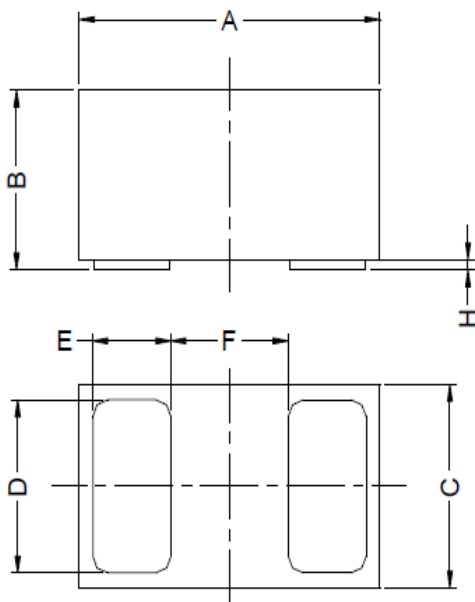
Ordering information

Marking codes



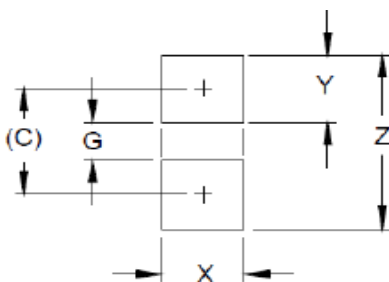
Part No.	Marking Code
FM05VB	E
Quantity	5,000pcs

Package information



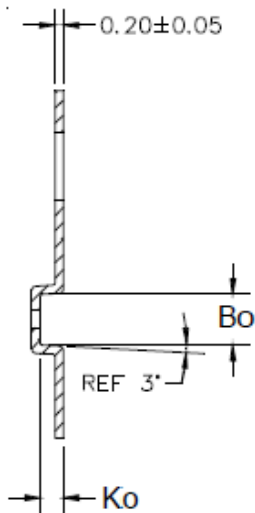
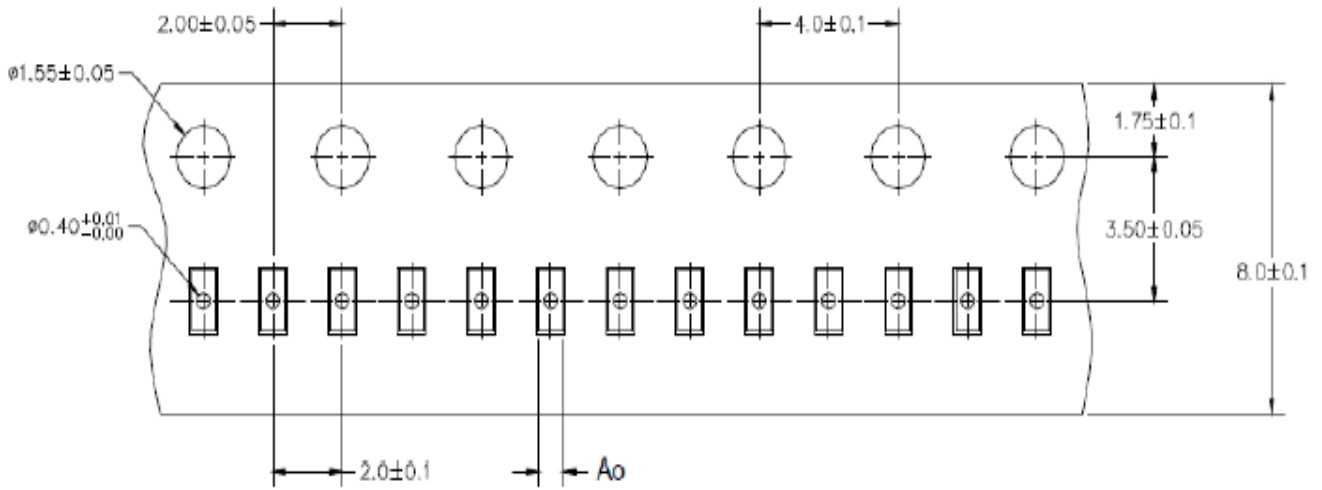
DFN1006-2			
Dim	Min	Typ	Max
A	0.95	1.00	1.075
B	0.47	0.50	0.53
C	0.55	0.60	0.675
D	0.45	0.50	0.55
E	0.20	0.25	0.30
F	-	0.40	-
H	0	0.03	0.05
All Dimensions in mm			

Pad Layout



DIMENSIONS		
DIM	INCHES	MILLIMETERS
C	(.033)	(0.85)
G	.012	0.30
X	.024	0.60
Y	.022	0.55
Z	.055	1.40

Tape & Reel information



A0	B0	K0
0.69 +/-0.10 mm	1.19 +/-0.10 mm	0.66 +/-0.10 mm

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